CALLS FOR ARTICLES FOR COMPUTER

Computer plans a May 2017 special issue on learning technologies.

In this special issue, mainstream educators, curriculum developers, learning-technology specialists, and others will identify best practices, the most forward-looking and effective educational and learning technologies, and related social-networking trends.

They can submit articles addressing, for example, openness, online or hybrid educational approaches, blended individualized and group instruction, collaborative methodologies, adaptive learning (using open data, big data, and/or cloud computing), deep learning, mobile learning, semantic computing methodologies, educational technology standards, and social issues.

This issue will also include selected contributions from both the IEEE Symposium on Computer Education and Learning Technologies, which is affiliated with the IEEE Computer Society’s Conference on Computers, Software, and Applications (COMPSAC); and the Computer Society-sponsored track on Computing Education Challenges at the IEEE Education Society’s Conference on Technology, Assessment, and Learning for Engineering.

Abstracts are due 1 September 2016 (mail to co-0517@computer.org), and articles are due 1 October 2016. Visit www.computer.org/web/computingnow/cocfp5 to view the complete call for papers.

Computer plans a June 2017 special issue on VLSI for the Internet of Things (IoT).

The IoT promises to revolutionize a wide range of applications. But capitalizing on the IoT will require a new generation of VLSI systems. IoT sensing and actuation devices must be extremely low cost while still delivering a complete system on chip (SoC)—capable of performing computation, security, and wireless communications—at extremely low power levels. Other types of edge devices can help close the gap in capabilities, cost, and energy usage between the traditional TCP/IP-based cloud and sensing/actuation nodes.

This new generation of IoT devices requires a very different approach to VLSI design at all levels of abstraction: technology, circuits, logic, architecture, and systems. While the microprocessor market is driven by complex functionality, resulting in large chips that reach clocking and thermal limits, IoT systems require low-cost, low-power SoCs.

Abstracts are due 1 October 2016 (mail to co-0617@computer.org), and articles are due 1 November 2016. Visit www.computer.org/web/computingnow/cocfp6 to view the complete call for papers.

CALLS FOR ARTICLES FOR OTHER IEEE CS PUBLICATIONS

IEEE Computer Graphics and Applications plans a May/June 2017 special issue on computational design and fabrication meeting computer graphics.

Computer graphics researchers are increasingly interested in the high-level analysis and processing of geometric objects, focusing more on their structure, semantics, and even functionalities than their geometric details.

This is leading researchers to study design problems in which machine computation can replace or contribute to manual efforts. Because of rapid advances in 3D printing technologies for manufacturing, much of this work addresses fabrication-related issues.

The guest editors seek papers from visual computing communities that address real-world problems related to the computational design and fabrication of 3D objects.

Articles are due 1 September 2016. Visit www.computer.org/web/computingnow/cgacfp3 to view the complete call for papers.

IEEE Transactions on Emerging Topics in Computing (TETC) plans the following theme sections for its September 2017 issue, with articles for each due 1 September 2016:


SUBMISSION INSTRUCTIONS

The Call and Calendar section lists conferences, symposia, and workshops that the IEEE Computer Society sponsors or cooperates in presenting.

Visit www.computer.org/conferences for instructions on how to submit conference or call listings as well as a more complete listing of upcoming computer-related conferences.

SUBMISSION INSTRUCTIONS

IEEE Transactions on Nanotechnology and IEEE Transactions on Emerging Topics in Computing plan a September 2017 joint special section on VLSI and nanotechnology design trends for computing innovations.

Topics of interest include VLSI design; low-power and power-aware design; testing, reliability, and fault tolerance; VLSI circuits; computer-aided design; emerging technologies; and post-CMOS VLSI.

Articles are due 30 September 2016. Visit www.computer.org/cms/Computer.org/transactions/cfps/cfp_tetcsi_vlsi_ndtci.pdf to view the complete call for papers.

IEEE Internet Computing plans a July/August 2017 special issue on energy-efficient datacenters.

In the last decade, datacenters have become the core of modern business environments as computation has moved into the cloud. Datacenters are among the US's fastest-growing electricity users. This costs businesses money, consumes limited energy resources, and contributes to environmental pollution.

Because of this, there's a demand for more energy-efficient datacenters. This special issue calls for research on various approaches that can enable their creation.

Brief article descriptions are due 28 September 2016 (mail to ic4-2017@computer.org), and articles are due 28 October 2016. Visit www.computer.org/web/computingnow/iccfp4 to view the complete call for papers.

IEEE Computer Graphics and Applications plans a July/August 2017 special issue on animation of natural virtual characters.

Virtual characters are used in a range of applications—from interfaces to games—in which they must effectively employ human nonverbal communication.

Building systems that can support these interactions involves both the automatic specification and generation of appropriate character motion, as well as coordination across communication modes and among multiple characters.

For this special issue, we solicit papers describing innovative character-animation techniques and models.

Articles are due 1 November 2016. Visit www.computer.org/web/computingnow/cgacfp4 to view the complete call for papers.

IEEE Software plans a July/August 2017 special issue on reliability engineering for software.

As the number of smart, interconnected devices in our cars and homes increases, engineers must increasingly consider software reliability in the connectivity tools and platforms they create. Reliability engineering emphasizes dependability, whether at a critical moment or throughout the software's life cycle.

This theme issue focuses on reliability challenges and successes in software engineering.

The guest editors seek articles reporting case studies, experience reports, practices, approaches, techniques, and guidelines, all involving practical software results.

Articles are due 1 December 2016. Visit www.computer.org/web/computingnow/swcfp4 to view the complete call for papers.

IEEE Transactions on Emerging Topics in Computing (TETC) plans the following special section for its
CALL AND CALENDAR

EVENTS IN 2016

OCTOBER 2016

NOVEMBER 2016

DECEMBER 2016

SEPTEMBER 2016
11–15 September: PACT 2016, Parallel Architectures and Compilation Techniques, Haifa, Israel; http://pactconf.org

OCTOBER 2016

NOVEMBER 2016

DECEMBER 2016
WF-IOT 2016

The IEEE 3rd World Forum on Internet of Things (WF-IOT) is sponsored by IEEE. WF-IOT’s theme this year is smart innovation for vibrant ecosystems.

The Internet of Things (IoT) envisions a highly net-worked future in which individual objects are integrated to interact with one another, allowing for communication between objects, as well as between humans and objects. This better enables people to control intelligent systems.

This year’s WF-IOT will examine key IoT innovations that will alter the direction of future research and applications. The forum is geared to industry leaders, academics, and decision-making government officials.


Oracle America, Inc. has openings for the following positions (all levels/types) in San Mateo County, including Redwood Shores, CA; Alameda County, including Pleasanton, CA; San Francisco, CA; Santa Clara County, including Santa Clara and San Jose, CA; and other locations in the San Francisco Bay Area. Some positions may allow for telecommuting.

Hardware Developers (HWD716): Evaluate reliability of materials, properties and techniques used in production; plan, design and develop electronic parts, components, integrated circuitry, mechanical systems, equipment and packaging, optical systems and/or DSP systems.

Product Managers (PM716): Participate in all software and/or hardware product development life cycle activities. Move software products through the software product development cycle from design and development to implementation, testing, and/or marketing.

Software Developers (SWD716): Design, develop, troubleshoot and/or test/QA software.

Applications Developers (APD716): Analyze, design, develop, troubleshoot and debug software programs for commercial or end user applications. Write code, complete programming and perform testing and debugging of applications.

Technical/Programmer Analysts (CSA716): Analyze user requirements to develop, implement, and/or support Oracle’s global infrastructure.

Consultants (TCONS716): Analyze requirements and deliver functional and technical solutions. Implement products and technologies to meet post-sale customer needs. Travel to various unanticipated sites throughout the U.S. required.

Sales Consultants (TSC716): Provide presales technical/functional support to prospective customers. Design, validate and present Oracle’s software solutions to include product concepts and future direction. Travel to various unanticipated sites throughout the U.S. required.

Software Developers (TSWD716): Design, develop, troubleshoot and/or test/QA software. Travel to various unanticipated sites throughout the U.S. required.

Applications Developers (TAPD716): Analyze, design, develop, troubleshoot and debug software programs for commercial or end user applications. Write code, complete programming and perform testing and debugging of applications. Travel to various unanticipated sites throughout the U.S. required.

Submit resume to applicant_us@oracle.com. Must include job#. Oracle supports workforce diversity.

TECHNOLOGY
Oracle America, Inc.